

High Temperature Silicon Carbide Power Schottky Diode

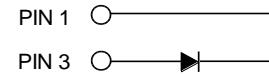
V_{RRM}	=	650 V
I_F (T_C=25°C)	=	4 A
Q_C	=	7 nC

Features

- 650 V Schottky rectifier
- 250 °C maximum operating temperature
- Zero reverse recovery charge
- Superior surge current capability
- Positive temperature coefficient of V_F
- Temperature independent switching behavior
- Lowest figure of merit Q_C/I_F
- Available screened to Mil-PRF-19500

Package

- RoHS Compliant



SMD0.5 / TO – 276 (Hermetic Package)

Advantages

- High temperature operation
- Improved circuit efficiency (Lower overall cost)
- Low switching losses
- Ease of paralleling devices without thermal runaway
- Smaller heat sink requirements
- Industry's lowest reverse recovery charge
- Industry's lowest device capacitance
- Ideal for output switching of power supplies
- Best in class reverse leakage current at operating temperature

Applications

- Down Hole Oil Drilling
- Geothermal Instrumentation
- Solenoid Actuators
- General Purpose High-Temperature Switching
- Amplifiers
- Solar Inverters
- Switched-Mode Power Supply (SMPS)
- Power Factor Correction (PFC)

Maximum Ratings at T_j = 250 °C, unless otherwise specified

Parameter	Symbol	Conditions	Values	Unit
Repetitive peak reverse voltage	V _{RRM}		650	V
Continuous forward current	I _F	T _C = 25 °C	4	A
Continuous forward current	I _F	T _C ≤ 225 °C	1	A
RMS forward current	I _{F(RMS)}	T _C ≤ 225 °C	2	A
Surge non-repetitive forward current, Half Sine Wave	I _{F,SM}	T _C = 25 °C, t _p = 10 ms	10	A
Non-repetitive peak forward current	I _{F,max}	T _C = 25 °C, t _p = 10 µs	65	A
I ² t value	∫I ² dt	T _C = 25 °C, t _p = 10 ms	0.5	A ² S
Power dissipation	P _{tot}	T _C = 25 °C	64	W
Operating and storage temperature	T _j , T _{stg}		-55 to 250	°C

Electrical Characteristics at T_j = 250 °C, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Diode forward voltage	V _F	I _F = 1 A, T _j = 25 °C	1.6			V
		I _F = 1 A, T _j = 250 °C	2.6			
Reverse current	I _R	V _R = 650 V, T _j = 25 °C	1	5	50	µA
		V _R = 650 V, T _j = 250 °C	5			
Total capacitive charge	Q _C	I _F ≤ I _{F,MAX}	7			nC
Switching time	t _s	dI _F /dt = 200 A/µs	76			ns
		T _j = 210 °C	< 17			
Total capacitance	C	V _R = 1 V, f = 1 MHz, T _j = 25 °C	76			pF
		V _R = 400 V, f = 1 MHz, T _j = 25 °C	12			
		V _R = 650 V, f = 1 MHz, T _j = 25 °C	12			

Thermal Characteristics

Thermal resistance, junction - case	R _{thJC}	3.55	°C/W
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Mechanical Properties

Mounting torque	M	0.6	Nm
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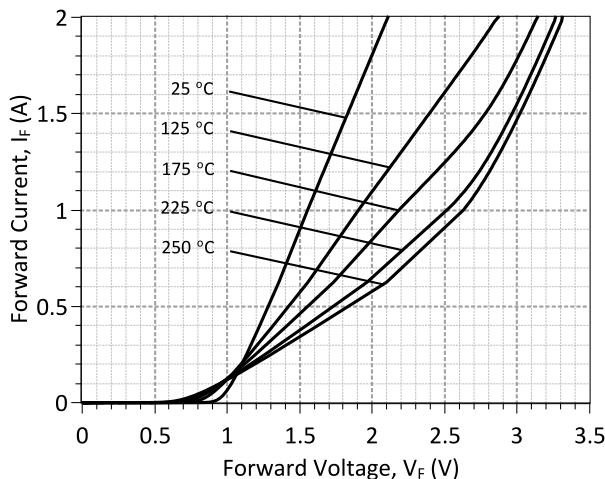


Figure 1: Typical Forward Characteristics

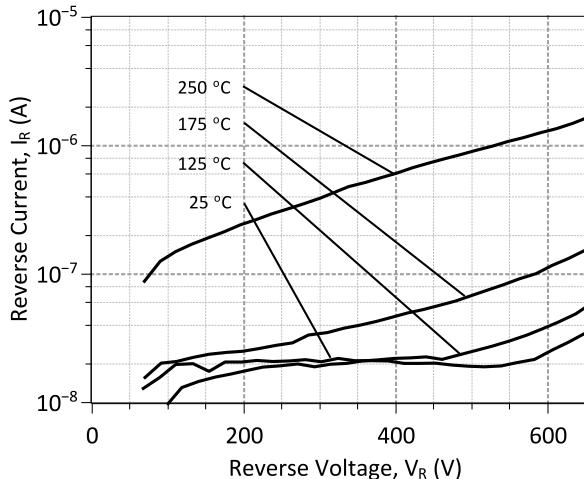


Figure 2: Typical Reverse Characteristics

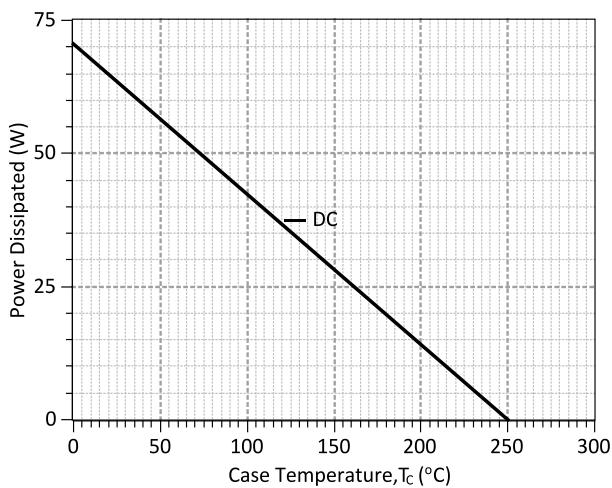


Figure 3: Power Derating Curve

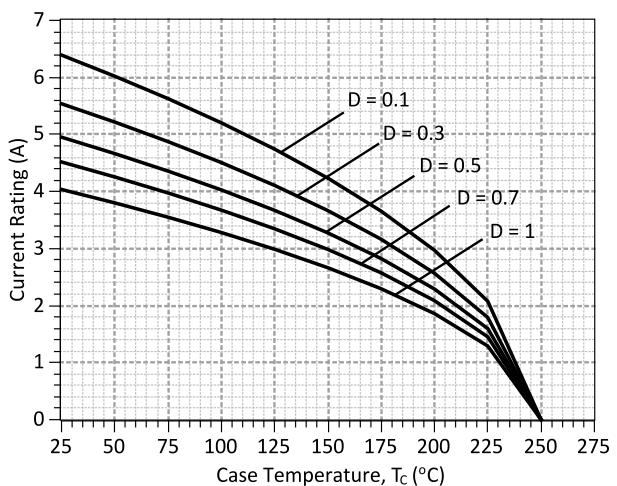


Figure 4: Current Derating Curves ($D = t_p/T$, $t_p = 400 \mu s$)
 (Considering worst case Z_{th} conditions)

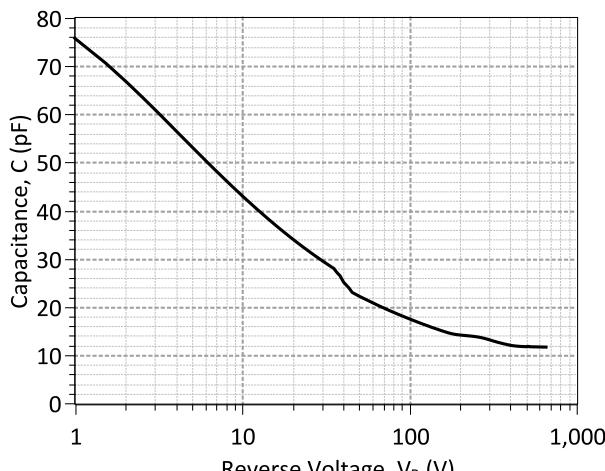


Figure 5: Typical Junction Capacitance vs Reverse Voltage Characteristics

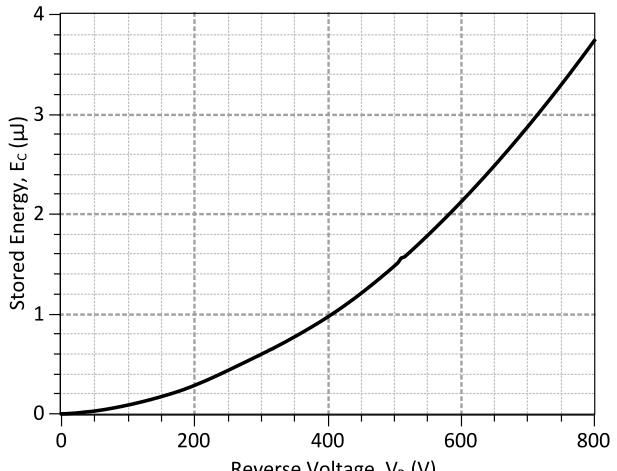


Figure 6: Typical Switching Energy vs Reverse Voltage Characteristics

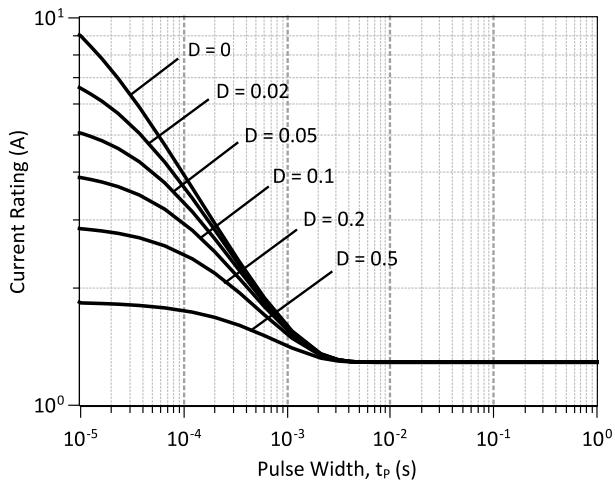


Figure 7: Current vs Pulse Duration Curves at $T_c = 225 \text{ } ^\circ\text{C}$

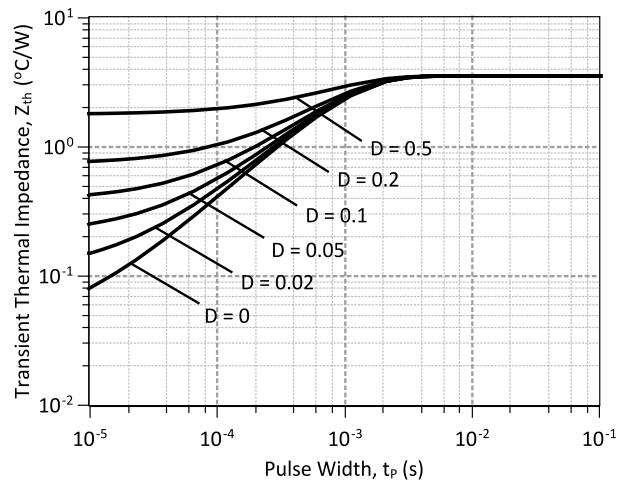
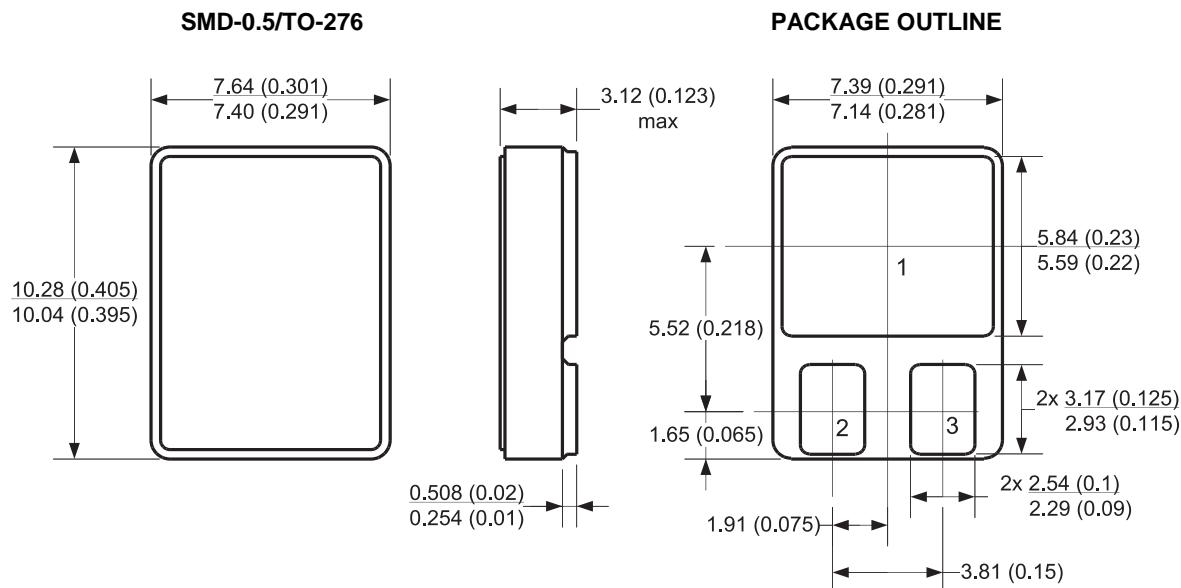


Figure 8: Transient Thermal Impedance

Package Dimensions:



NOTE

1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.
2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS



1N8031-GA

Revision History			
Date	Revision	Comments	Supersedes
2014/08/26	1	Updated Electrical Characteristics	
2012/04/24	0	Initial release	

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SPICE Model Parameters

This is a secure document. Copy this code from the SPICE model PDF file on our website into a SPICE software program for simulation of the 1N8031-GA.

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* MODEL OF GeneSiC Semiconductor Inc.  
*  
* $Revision: 1.0 $  
* $Date: 05-SEP-2013 $  
  
* GeneSiC Semiconductor Inc.  
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* Dulles, VA 20166  
  
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* OF ANY KIND EITHER EXPRESSED OR IMPLIED, INCLUDING BUT NOT LIMITED  
* TO ANY IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A  
* PARTICULAR PURPOSE."  
* Models accurate up to 2 times rated drain current.  
  
* Start of 1N8031-GA SPICE Model  
  
.SUBCKT 1N8031 ANODE KATHODE  
D1 ANODE KATHODE 1N8031_25C; Call the Schottky Diode Model  
D2 ANODE KATHODE 1N8031_PIN; Call the PiN Diode Model  
.MODEL 1N8031_25C D  
+ IS      3.57E-18      RS      0.49751  
+ TRS1    0.0057      TRS2    2.40E-05  
+ N       1           IKF     322  
+ EG      1.2          XTI     3  
+ CJO     9.12E-11     VJ      0.371817384  
+ M       1.527759838   FC      0.5  
+ TT      1.00E-10     BV      650  
+ IBV     1.00E-03     VPK     650  
+ IAVE    1           TYPE    SiC_Schottky  
+ MFG     GeneSiC_Semiconductor  
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+ FC      0.5          TT      0  
+ BV      650          IBV     1.00E-03  
+ VPK     650          IAVE    1  
+ TYPE    SiC_Pin  
.ENDS  
  
* End of 1N8031-GA SPICE Model
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